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EFS ID: 54326
Application ID: 10680280
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METHOD FOR MANUFACTURING
THE SAME
First Named Inventor: Jong Paek
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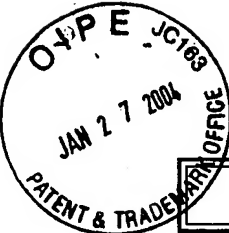


TRANSMITTAL

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Stylesheet Version v1.1.0

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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml		us-ids.dtd		us-ids.xsl
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Electronic Version v18
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<h2>US Patent Documents</h2> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>5221642</td><td>1993-06-22</td><td>BURNS</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5250841</td><td>1993-10-05</td><td>SLOAN ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5252853</td><td>1993-10-12</td><td>MICHII</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>5258094</td><td>1993-11-02</td><td>FURUI ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>5266834</td><td>1993-11-30</td><td>NISHI ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>5273938</td><td>1993-12-28</td><td>LIN ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>5278446</td><td>1994-01-11</td><td>NAGARAJ ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>5277972</td><td>1994-01-11</td><td>SAKUMOTO ET AL.</td><td></td><td></td><td></td></tr><tr><td></td><td>9</td><td>5279029</td><td>1994-01-18</td><td>BURNS</td><td></td><td></td><td></td></tr></tbody></table>						init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	5221642	1993-06-22	BURNS					2	5250841	1993-10-05	SLOAN ET AL.					3	5252853	1993-10-12	MICHII					4	5258094	1993-11-02	FURUI ET AL.					5	5266834	1993-11-30	NISHI ET AL.					6	5273938	1993-12-28	LIN ET AL.					7	5278446	1994-01-11	NAGARAJ ET AL.					8	5277972	1994-01-11	SAKUMOTO ET AL.					9	5279029	1994-01-18	BURNS			
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Signature

Examiner Name	Date